

KYUSHU UNIVERSI

Study of silicon sensors for precise timing measurement

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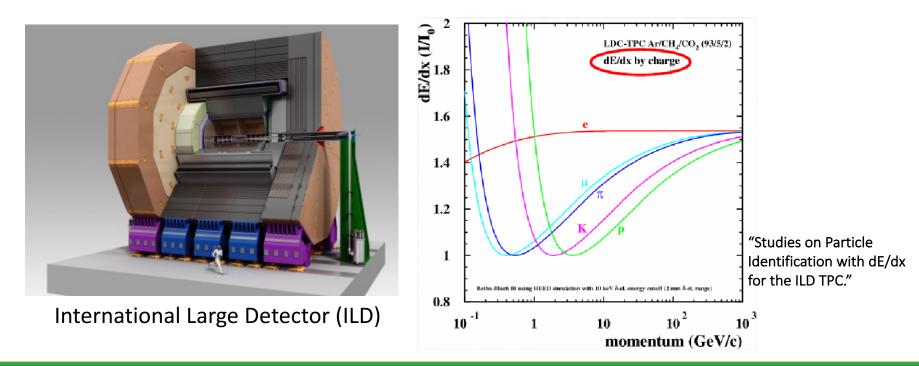


Microelectronic

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International Large Detector (ILD)

- One of the detectors placed at the collision point of ILC
- Mainly charged particles are detected by tracking detectors, and neutral particles are detected by calorimeters
- In the TPC, dE/dx is calculated by the collected charge to identify the particles



Identification of particles

• Time of flight

Particles have differences of flight time depending on their mass

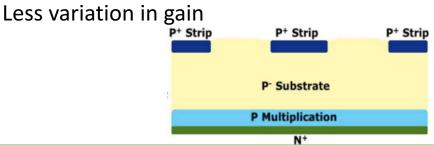
Particle	mass	$eta=rac{ u}{c}$ (5 GeV)
К	494 MeV/ <i>c</i> ²	0.9951
π	139 MeV/ <i>c</i> ²	0.9996

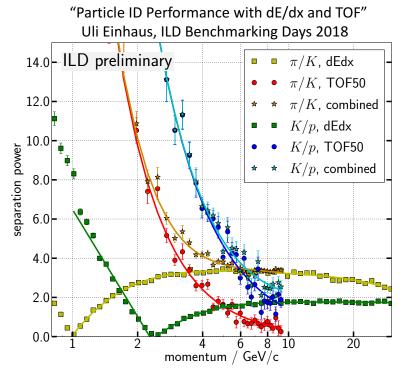
In order to identify K and π , we need to have time resolution less than 50 psec

- ➤ LGAD (Low Gain Avalanche Diode)
 → The time resolution : ~30 psec (in ATLAS study)
- Reach-through type
- Fast charge collection speed
 - Insensitive area



Multiplication layer covered bottom layer





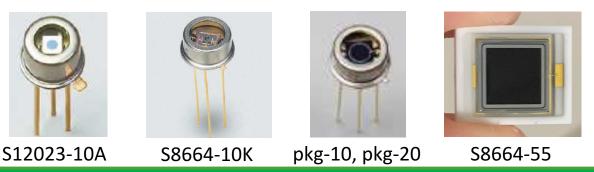
Avalanche Photo Diode

LGADs have same structure as APDs

We study APDs for LGAD development

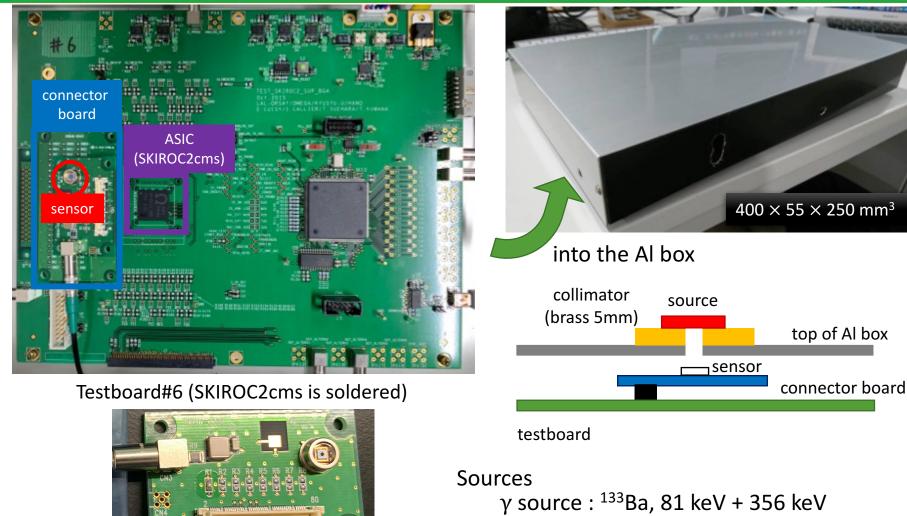
Model number	Туре	V _{br}	Size	
S12023-10A	Reach-through	139 V	ϕ 1 mm	
S8664-10K	Inverse	417 V	ϕ 1 mm	
pkg-10	Reach-through	about 250 V	ϕ 1 mm	
pkg-20	Reach-through	about 120 V	ϕ 1 mm	
S2384	Reach-through	159 V	φ 2 mm	
S3884	Reach-through	189 V	ϕ 1.5 mm	
S8664-20K	Inverse	425 V	φ 2 mm	
S8664-55	Inverse	433 V	$5 \times 5 \text{ mm}^2$	

LCWS2019 in Sendai



LGAD prototype (for LHC)

Set up of DAQ



(compton edge : 207 keV)

 β source : ⁹⁰Sr, 2.2 MeV (Max)

connector board (with S8664-10K)

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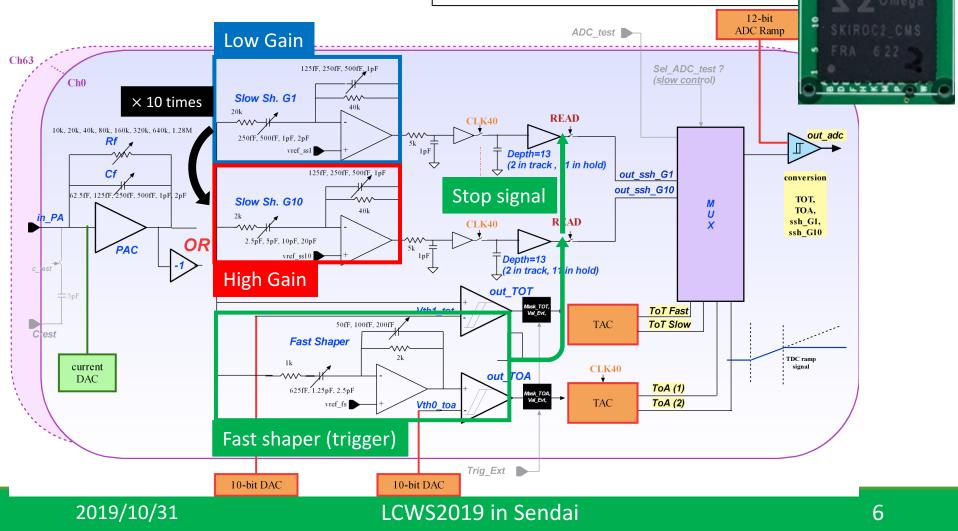
SKIROC2cms

- SKIROC2cms is an ASIC to readout signals from sensors
- Time over threshold and Time of arrival can be acquired

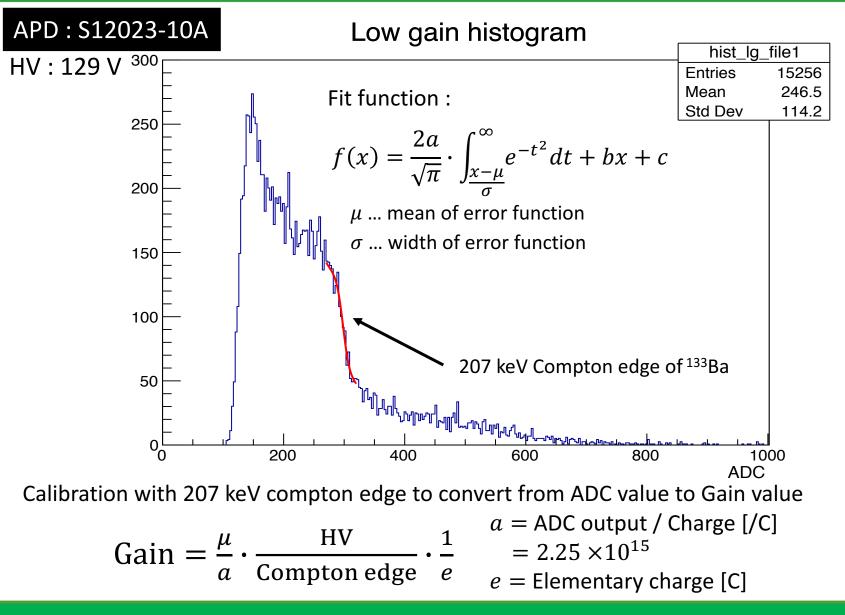
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Preamp polarity can be changed



Measurement using γ source



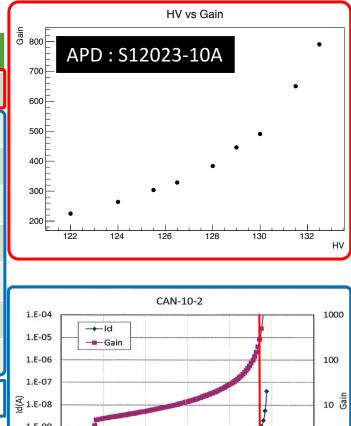
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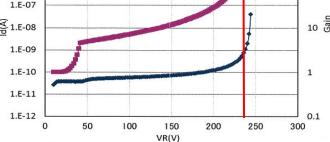
Set up of DAQ

Measurement

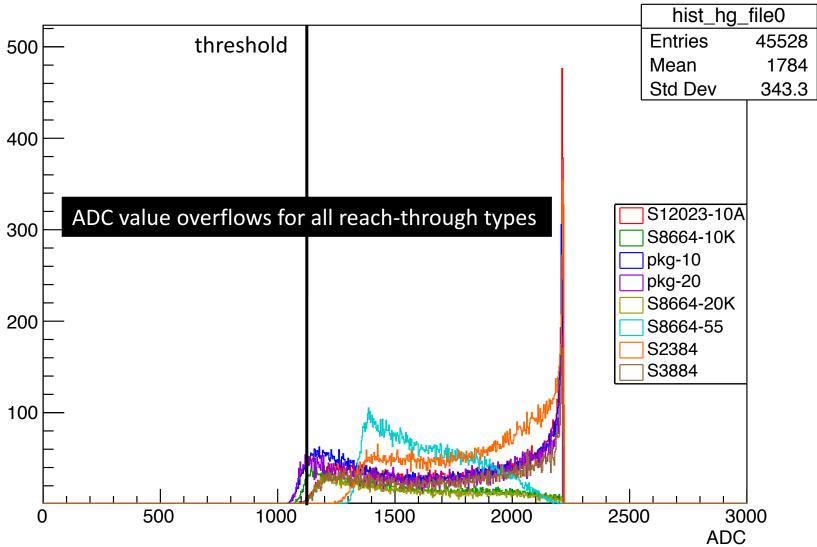
Model number	Туре	HV	Gain at each HV
S12023-10A	Reach-through	129 V	520 (Measured value)
S8664-10K	Inverse	407 V	about 500~1000
pkg-10	Reach-through	240 V	about 1000
pkg-20	Reach-through	110 V	about 1000
S2384	Reach-through	149 V	about 1000
S3884	Reach-through	179 V	about 1000
S8664-20K	Inverse	415 V	about 500~1000
\$8664-55	Inverse	415 V	about 500~1000
		[Hamamatsu datasheets

- S12023-10 : The Gain value is measured by DAQ with the γ source
- Other APDs : The Gain value is referenced by datasheet



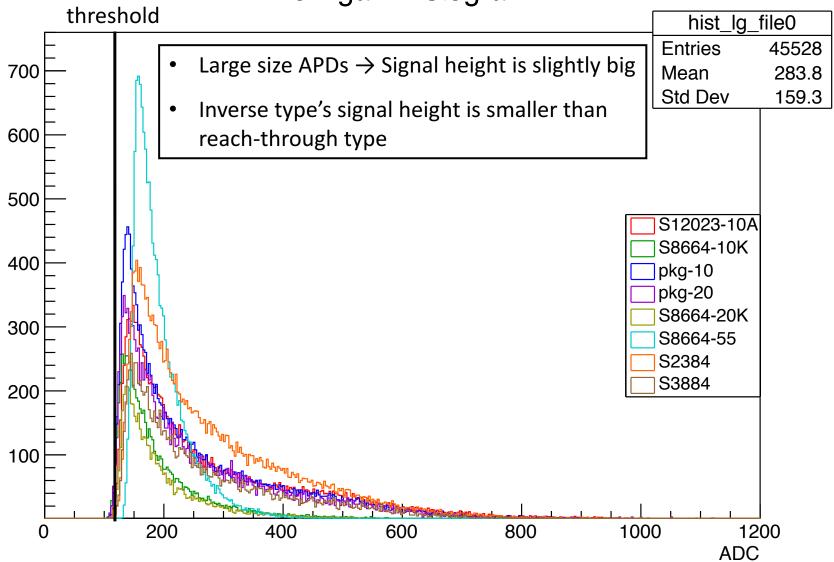


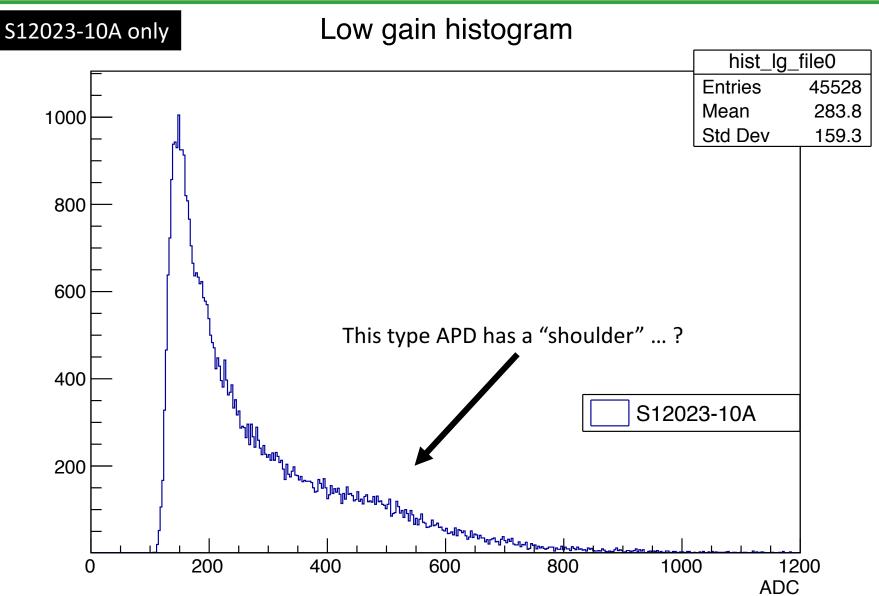
High gain histogram



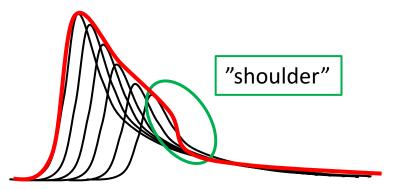
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Low gain histogram





Due to the gain variation inside the APD, signals by ⁹⁰Sr will be landau distribution for each gain (such as black lines), and the total distribution can be like red line



The "shoulder" will be made by the landau distribution of the maximum gain

The active thickness can be calculated using the "shoulder"

The relation between Charge and ADC output of SKIROC2cms are known (such as right figure)

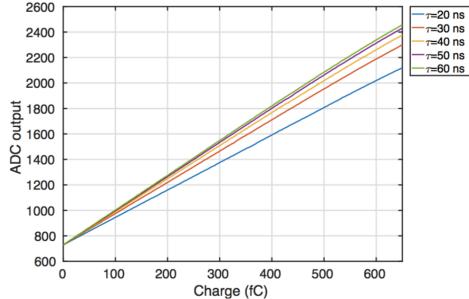
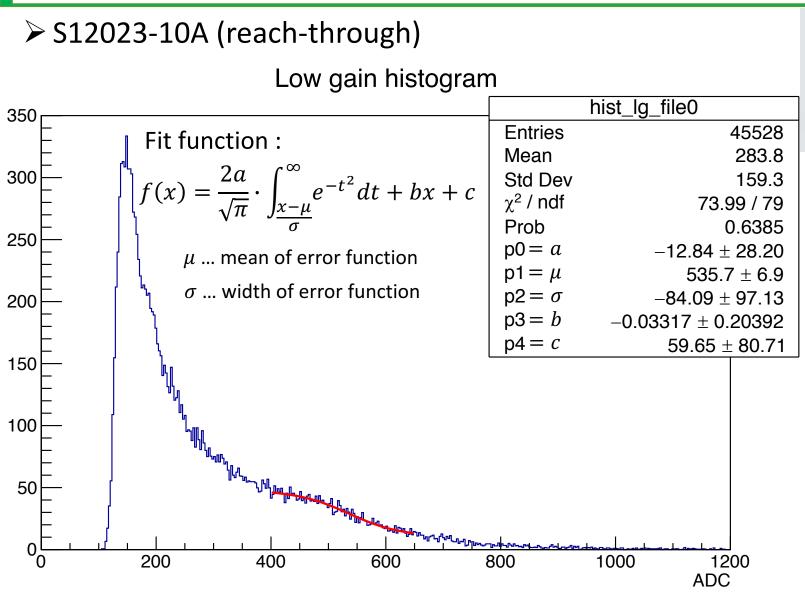


Figure 19: Low-gain transfer function for different shaper settings.



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S12023-10A

- Low gain histogram Active thickness A MIP particle makes 76 electron and 1000 hole pairs per 1 μ m in a silicon sensor 800 600 Active thickness =400 $\frac{\mu}{a} \cdot \frac{1}{\text{Gain}} \cdot \frac{1}{76 \cdot e} \, \left[\mu \text{m}\right]$ 200 a = ADC output / Charge [/C] 200 800 400 600 $= 2.25 \times 10^{15}$
 - $\mu = \text{mean of fit function}$
 - e = Elementary charge [C]

Active thickness of S12023-10A : ~40 μm

hist lg_file0

1200 ADC

45528

283.8

159.3

Entries

Std Dev

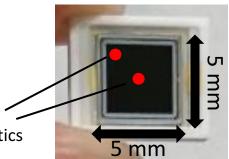
Mean

S12023-10A

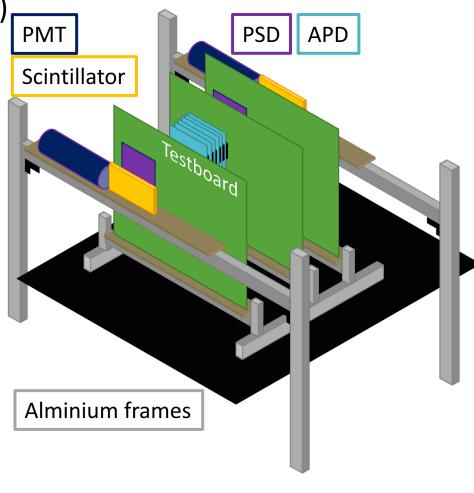
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Preparation of Test Beam

- ✓ Place : ELPH (Tohoku University)
- Basic characteristics
 - Active thickness
 - Comparison between Reach-through type and Inverse type
- Time resolution
 - Measurement time resolution using the three identical type APDs
- Position dependence in sensor
 - ADC measurement at several points in a sensor

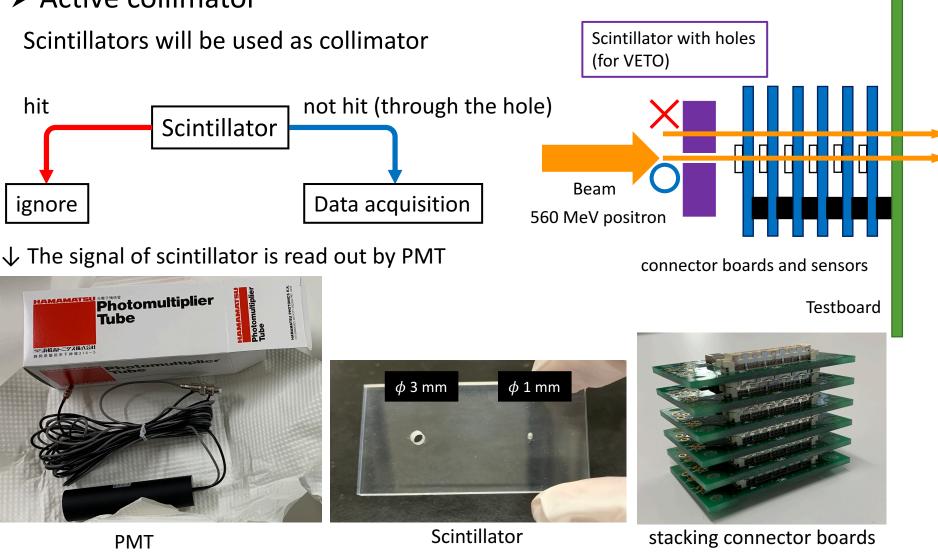


Compare the characteristics at the center and corner



Preparation of Test Beam

Active collimator



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Summary

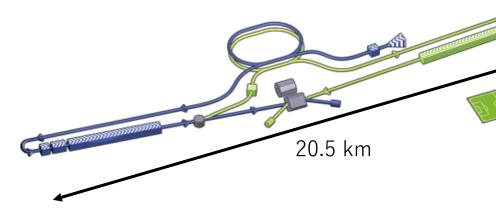
- Signal heights are measured with 8 types of APDs for development of LGADs
- SKIROC2cms was used to take data
- Differences between reach-through type and inverse type were obtained
- In S12023-10A (reach-through), the active thickness was estimated
- Test Beam preparation is ongoing
- > Next step
 - Analysis of the Test Beam data
 - Producing the LGAD prototype for ILC

Back up

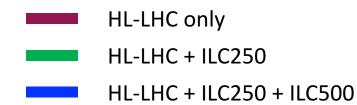
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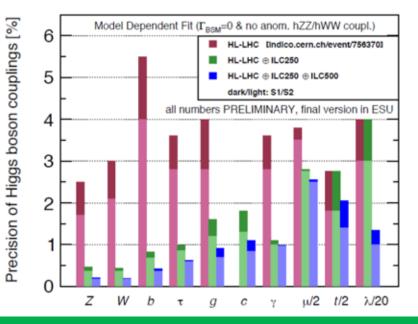
International Linear Collider (ILC)

- > What is the ILC ?
 - Electron and positron collider
 - Site : Mt. Kitakami, Japan
 - $\sqrt{s} = 250 \text{ GeV}$ \rightarrow Up to 1 TeV in the future
 - Length: about 20 km



• Search for new physics with precise measurement of Higgs and other particles

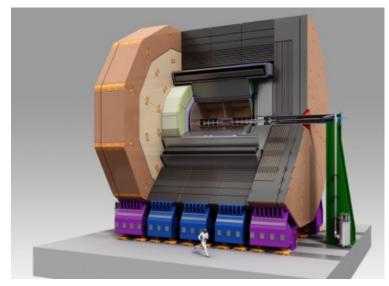




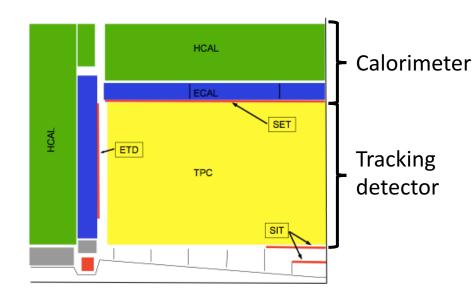
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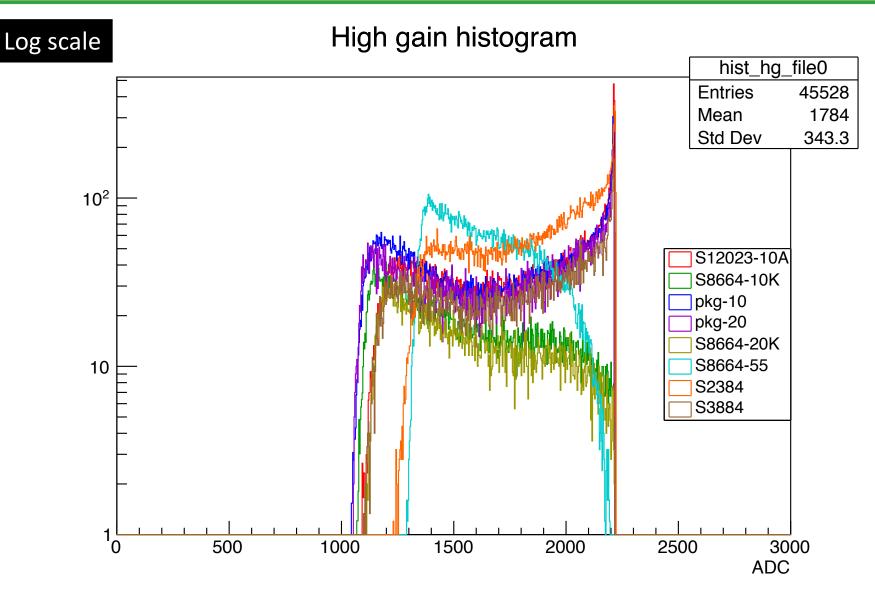


International Large Detector (ILD)



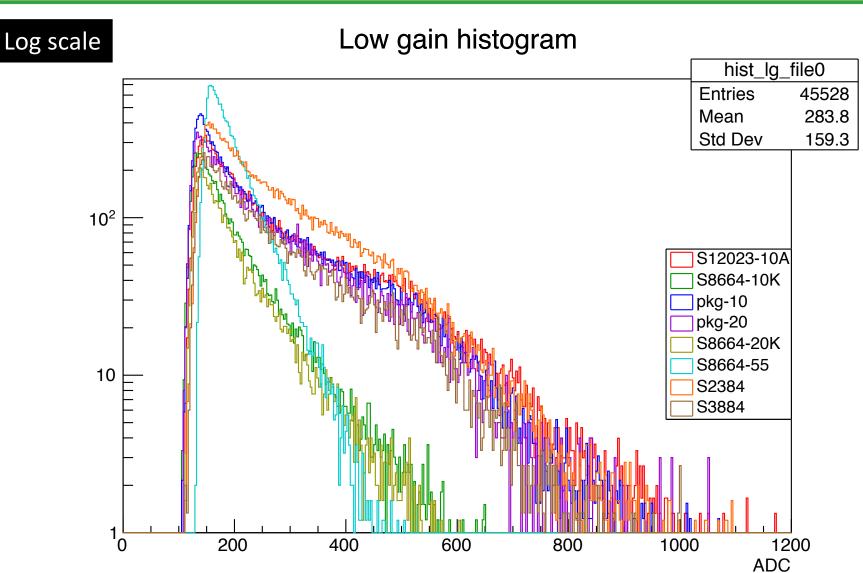
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Measurement using β source



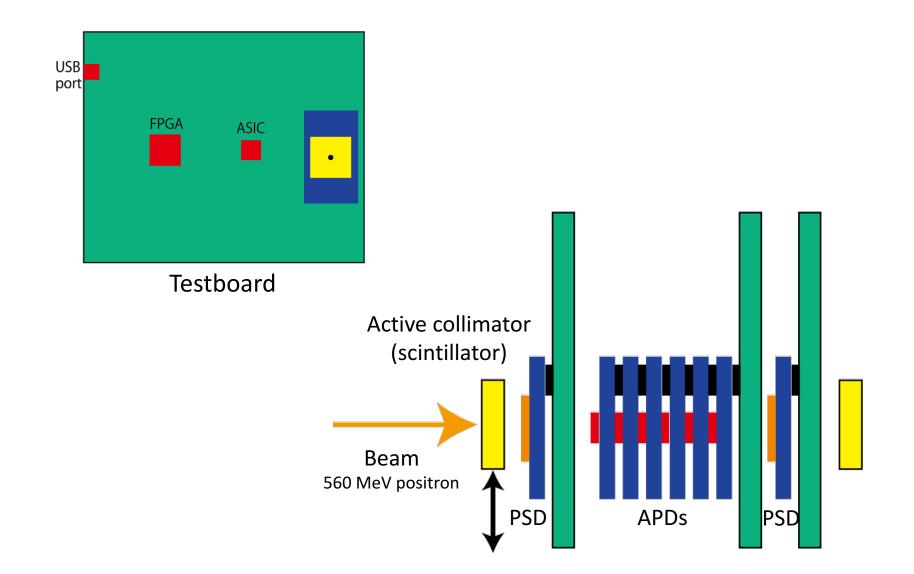
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Measurement using β source



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Test Beam Overview



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